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SCHWEGMAN ■ LUNDBERG ■ WOESSNER ■ KLUTH

PATENT, TRADEMARK & COPYRIGHT ATTORNEYS

P.O. Box 2938

Minneapolis, MN 55402

Telephone (612) 373-6900

Facsimile (612) 339-3061

October 3, 2005

Time: 1:37 PM
(Minneapolis, Minn.)TO: Commissioner for Patents
Attn: Fetsum Abraham
Patent Examining Corps
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P.O. Box 1450
Alexandria, VA 22313-1450FROM: David R. CochranOUR REF: 303.610US1TELEPHONE: 571-272-1911FAX NUMBER (571) 273-8300*** Please deliver to Examiner Fetsum Abraham in Art Unit 2826. ***Document(s) Transmitted: Supplemental Information Disclosure Statement (2 pages), Form 1449 (1 pg.), Authorization to charge Deposit Account 19-0743 in the amount of \$180.00 for consideration of SIDS, Communication Concerning Related Applications (1 pg.)Total pages of this transmission, including cover letter: 5 pgs.

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In re. Patent Application of: Paul A. FarrarSerial No.: 09/382,524Filed: August 25, 1999Title: HYDROPHOBIC FOAMED INSULATORS FOR HIGH DENSITY CIRCUITSExaminer: Fetsum AbrahamGroup Art Unit: 2826Docket No.: 303.610US1RECEIVED
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By: David R. Cochran
Name: David R. Cochran
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S/N 09/382,524

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar
Serial No.: 09/382,524
Filed: August 25, 1999
Title: HYDROPHOBIC FOAMED INSULATORS FOR HIGH DENSITY CIRCUITS

Examiner: Fetsum Abraham
Group Art Unit: 2826
Docket: 303.610US1

COMMUNICATION CONCERNING RELATED APPLICATION(S)

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicant would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date/Issue Date</u>	<u>Attorney Docket</u>	<u>Title</u>
10/730641 6953983	December 8, 2003	1303.041US2	A SEMICONDUCTOR DEVICE COMPRISING LOW DIELECTRIC CONSTANT STI WITH SOI DEVICES
10/929632	August 30, 2004	303.681US2	POLYNORBORNENE FOAM INSULATION FOR INTEGRATED CIRCUITS
10/931510	September 1, 2004	303.603US2	PACKAGING OF ELECTRONIC CHIPS WITH AIR-BRIDGE STRUCTURES
11/216486	August 31, 2005	303.603US3	PACKAGING OF ELECTRONIC CHIPS WITH AIR-BRIDGE STRUCTURES


Continuations and divisionals may be later filed on the cases listed above, or cited to the Examiner in any previous Communication Concerning Related Applications. Applicants request that the Examiner review all continuations and divisionals of the above-listed or previously-cited patent applications before allowing the claims of the present patent application.

Respectfully submitted,
PAUL A. FARRAR

By Applicant's Representatives,
SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 371-2157

Date 3 October 2005

By


David R. Cochran
Reg. No. 46,632

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